

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT3408927

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SOONHYUN PARK	06/18/2015
CHEOLWOONG SHIN	06/18/2015
HONGSIK KIM	06/18/2015
JINKI MIN	06/18/2015
SEUNGHWAN SONG	06/18/2015
BYUNGHYUN YI	06/18/2015
JIYOUN CHA	06/18/2015
RECEIVING PARTY DATA	
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City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	150-721
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29531063
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NAME OF SUBMITTER:	ROBERT J. GOODELL
SIGNATURE:	/Robert J. Goodell/
DATE SIGNED:	06/23/2015

Total Attachments: 2

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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

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for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Application No. _____); and

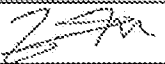
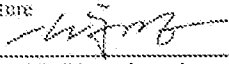
WHEREAS, LG ELECTRONICS INC., a corporation of Republic of Korea, whose post office address is 128, Yeoui-daero, Yeongdeungpo-gu, Seoul, 150-721, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

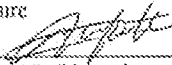
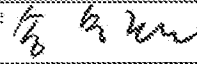
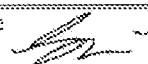
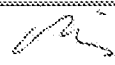
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of First Assignor Soonhyun PARK	Assignor's Signature 	Date June 16, 2015
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Full Name of Second Assignor Cheolwoong SHIN	Assignor's Signature 	Date June 18, 2015
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Names of additional inventors attached ☒ Yes ☐ No		

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Full Name of Fourth Assignor Jinki MIN	Assignor's Signature 	Date June 18, 2015
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Full Name of Fifth Assignor Seunghwan SONG	Assignor's Signature 	Date June 18, 2015
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Full Name of Seventh Assignor Jiyoun CHA	Assignor's Signature 	Date June 18, 2015
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Names of additional inventors attached ☐ Yes ☒ No		